

FPP Multi-Physics Package Compiler

Co-optimizes electrical, power, thermal, mechanical, yield, test and cost constraints

IP-157 · Architecture IP · Architecture

Function and architecture

- Co-optimizes electrical
- power
- thermal
- mechanical
- yield
- test and cost constraints

Integration summary

FPP Multi-Physics Package Compiler integration role: Package compiler. Documented composition: Co-optimizes electrical, power, thermal, mechanical, yield, test and cost constraints.

Technical record

Canonical identity	IP-157
Responsibility	Package compiler
Documented building blocks	Co-optimizes electrical, power, thermal, mechanical, yield, test and cost constraints
Delivery boundary	Architecture
Evidence scope	Architecture IP

Delivery and release binding

- Interface version and parameter set
- Clock/reset domains and integration constraints
- Companion memory, PHY and software requirements
- Verification collateral and acceptance criteria

Confirm for the selected release: Node/library binding, Clock/reset limits, Physical and protocol dependencies, Artifact hashes, Acceptance criteria.

Evidence and qualification

Canonical technology and its architecture/integration role are recorded. The offered delivery is confirmed against the exact release before licensing.

No node-port, silicon-performance, standards certification or analog qualification is inherited from a related product.

Canonical status: Architecture

Source basis: Bible v7.42 IP-157

Evaluation and licensing

Evaluation: Evaluate an individual IP configuration. Production: Named-design production license. Custom work: Node binding or derivative integration. Rights, pricing, support and acceptance criteria are agreed for the exact scope.

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